# 2SC3974

### Silicon NPN triple diffusion planar type

For high breakdown voltage high-speed switching

### ■ Features

- High-speed switching
- ullet High collector-base voltage (Emitter open)  $V_{CBO}$
- Wide safe operation area
- Satisfactory linearity of forward current transfer ratio h<sub>FE</sub>
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	800	V	
Collector-emitter voltage (E-B short)	V <sub>CES</sub>	800	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	500	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	8	V	
Base current	$I_{B}$	4	A	
Collector current	$I_{C}$	7	A	
Peak collector current	I <sub>CP</sub>	15	A	
Collector power dissipation	$P_{C}$	80	W	
$T_a = 25^{\circ}C$		3.0		
Junction temperature	$T_j$	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	

# Unit: mm 15.0±0.3 11.0±0.2 4 3.2±0.1 5.0±0.2 (3.2) 2.0±0.1 1.1±0.1 0.6±0.2 1.1±0.1

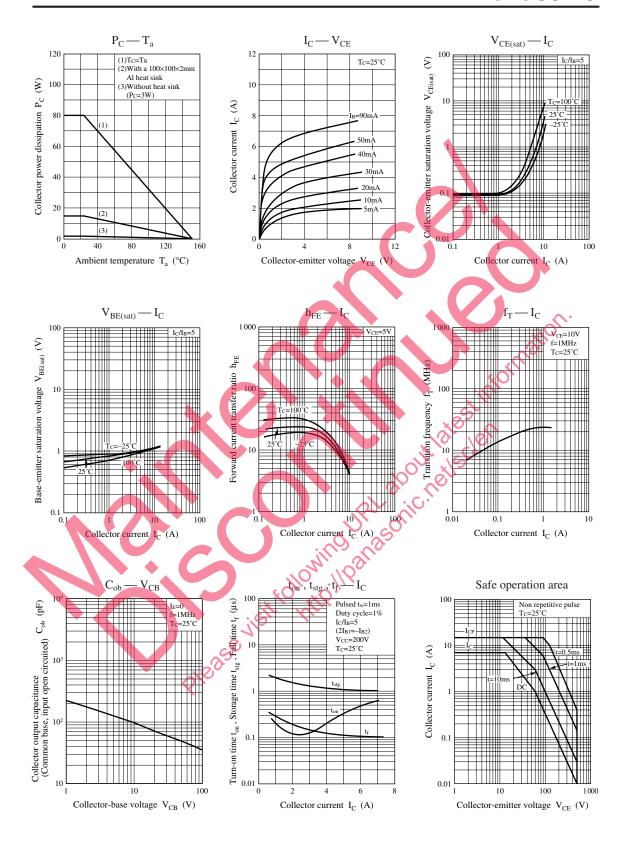
### ■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_{\rm C} = 10  \text{mA}, I_{\rm B} = 0$	500			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 800 \text{ V}, I_E = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 5 \text{ V}, I_C = 0$			100	μΑ
Forward current transfer ratio	$h_{EE1}$	$V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ A}$	15			_
	$h_{\mathrm{FE2}}$	$V_{CE} = 5 \text{ V}, I_{C} = 4 \text{ A}$	8			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 4 A, I_B = 0.8 A$			1.0	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 4 \text{ A}, I_B = 0.8 \text{ A}$			1.5	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time	t <sub>on</sub>	$I_C = 4 A$			1.0	μs
Storage time	t <sub>stg</sub>	$I_{B1} = 0.8 \text{ A}, I_{B2} = -1.6 \text{ A}$			3.0	μs
Fall time	$t_{\rm f}$	$V_{CC} = 200 \text{ V}$			0.3	μs

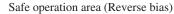
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

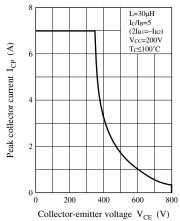
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## **Panasonic**

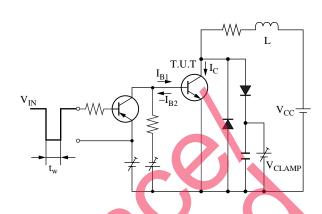


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### Safe operation area (Reverse bias) measuring circuit





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